



## GENERAL DESCRIPTION

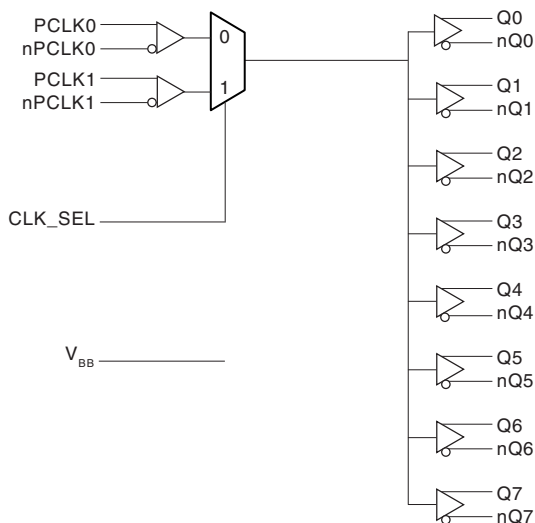


The ICS853310 is a low skew, high performance 1-to-8 Differential-to-3.3V LVPECL/ECL Fanout Buffer and a member of the HiPerClockS™ family of High Performance Clock Solutions from ICS. The PCLKx, nPCLKx pairs can accept LVPECL, LVDS, CML and SSTL differential input levels. The ICS853310 is characterized to operate from a 3.3V power supply. Guaranteed output and part-to-part skew characteristics make the ICS853310 ideal for those clock distribution applications demanding well defined performance and repeatability.

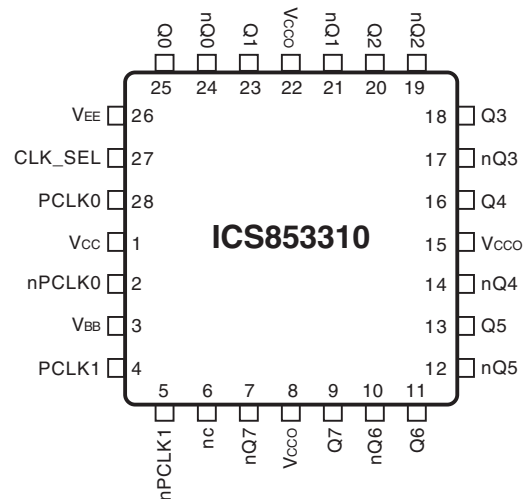
## FEATURES

- Eight differential 3.3V LVPECL / ECL outputs
- Two selectable differential LVPECL input pairs
- PCLKx, nPCLKx pairs can accept the following differential input levels: LVPECL, LVDS, CML, SSTL
- Output frequency: >2GHz (typical)
- Translates any single ended input signal to 3.3V LVPECL levels with resistor bias on nPCLKx input
- Output skew: 50ps (maximum)
- Part-to-part skew: 200ps (maximum)
- Propagation delay: 900ps (maximum)
- LVPECL mode operating voltage supply range:  $V_{CC} = 3V$  to  $3.8V$ ,  $V_{EE} = 0V$
- ECL mode operating voltage supply range:  $V_{CC} = 0V$ ,  $V_{EE} = -3V$  to  $-3.8V$
- $-40^{\circ}C$  to  $85^{\circ}C$  ambient operating temperature
- Available in both standard and lead-free RoHS-compliant packages

## BLOCK DIAGRAM



## PIN ASSIGNMENT



**28-Lead PLCC**

11.6mm x 11.4mm x 4.1mm package body

**V Package**

Top View



**TABLE 1. PIN DESCRIPTIONS**

Number	Name	Type		Description
1	$V_{CC}$	Power		Core supply pin.
2	nPCLK0	Input	Pullup/ Pulldown	Inverting differential LVPECL clock input. $V_{CC}/2$ .
3	$V_{BB}$	Output		Bias voltage.
4	PCLK1	Input	Pulldown	Non-inverting differential LVPECL clock input.
5	nPCLK1	Input	Pullup/ Pulldown	Inverting differential LVPECL clock input. $V_{CC}/2$ .
6	nc	Unused		No connect.
7, 9	nQ7, Q7	Output		Differential output pair. LVPECL interface levels.
8, 15, 22	$V_{CCO}$	Power		Output supply pins.
10, 11	nQ6, Q6	Output		Differential output pair. LVPECL interface levels.
12, 13	nQ5, Q5	Output		Differential output pair. LVPECL interface levels.
14, 16	nQ4, Q4	Output		Differential output pair. LVPECL interface levels.
17, 18	nQ3, Q3	Output		Differential output pair. LVPECL interface levels.
19, 20	nQ2, Q2	Output		Differential output pair. LVPECL interface levels.
21, 23	nQ1, Q1	Output		Differential output pair. LVPECL interface levels.
24, 25	nQ0, Q0	Output		Differential output pair. LVPECL interface levels.
26	$V_{EE}$	Power		Negative supply pin.
27	CLK_SEL	Input	Pulldown	Clock Select input. When HIGH, selects PCLK1, nPCLK1 inputs. When LOW, selects PCLK0, nPCLK0 inputs. LVCMOS / LVTTTL interface levels.
28	PCLK0	Input	Pulldown	Non-inverting differential LVPECL clock input.



**ABSOLUTE MAXIMUM RATINGS**

Supply Voltage, $V_{CC}$	4.6V (LVPECL mode, $V_{EE} = 0$ )
Negative Supply Voltage, $V_{EE}$	-4.6V (LVECL mode, $V_{CC} = 0$ )
Inputs, $V_I$ (LVPECL mode)	-0.5V to $V_{CC} + 0.5$ V
Inputs, $V_I$ (LVECL mode)	0.5V to $V_{EE} - 0.5$ V
Outputs, $I_O$	
Continuous Current	50mA
Surge Current	100mA
$V_{BB}$ Sink/Source, $I_{BB}$	$\pm 0.5$ mA
Operating Temperature Range, $T_A$	-40°C to +85°C
Storage Temperature, $T_{STG}$	-65°C to 150°C
Wave Solder, $T_{SOL}$	265°C

**NOTE:** Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

**TABLE 2A. LVPECL POWER SUPPLY DC CHARACTERISTICS,  $V_{CC} = 3V$  TO  $3.8V$ ;  $V_{EE} = 0V$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{CC}$	Core Supply Voltage		3.0	3.3	3.8	V
$V_{CCO}$	Output Supply Voltage		3.0	3.3	3.8	V
$I_{EE}$	Power Supply Current				70	mA

**Table 2B. LVPECL DC Characteristics,  $V_{CC} = 3.3V$ ;  $V_{EE} = 0V$**

Symbol	Parameter	-40°C			25°C			85°C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$V_{OH}$	Output High Voltage; NOTE 1	2.175	2.275	2.38	2.225	2.295	2.37	2.295	2.22	2.365	V
$V_{OL}$	Output Low Voltage; NOTE 1	1.405	1.545	1.68	1.425	1.52	1.615	1.44	1.535	1.63	V
$V_{IH}$	Input High Voltage (Single-Ended)	2.075		2.36	2.075		2.36	2.075			V
$V_{IL}$	Input Low Voltage (Single-Ended)	1.43		1.765	1.43		1.765	1.43		1.765	V
$V_{BB}$	Output Voltage Reference; NOTE 2	1.86		1.98	1.86		1.98	1.86		1.98	mV
$V_{PP}$	Peak-to-Peak Input Voltage	500		1000	500		1000	500		1000	mV
$V_{CMR}$	Input High Voltage Common Mode Range; NOTE 3	1.8		2.9	1.8		2.9	1.8		2.9	V
$I_{IH}$	Input High Current PCLK0, PCLK1 nPCLK0, nPCLK1 CLK_SEL			150			150			150	$\mu$ A
$I_{IL}$	Input Low Current PCLK0, PCLK1, nPCLK0, nPCLK1 CLK_SEL	-150			-150			-150			$\mu$ A

NOTE 1: Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary  $\pm 0.3V$ . Please refer to Parameter Measurement Information, "Output Load AC Test Circuit".

NOTE 2: Outputs terminated with  $50\Omega$  to  $V_{CCO} - 2V$ .

NOTE 3:  $V_{CMR}$  min varies 1:1 with  $V_{EE}$ , max varies 1:1 with  $V_{CC}$ .  $V_{CMR}$  is defined as the range within which the  $V_{IH}$  level may vary, with the device still meeting the propagation delay specification. The  $V_{IL}$  level must be such that the peak-to-peak voltage is less than 1V and greater than or equal to  $V_{pp}(\min)$ .



**TABLE 2C. LVECL POWER SUPPLY DC CHARACTERISTICS,  $V_{CC} = 0V$ ;  $V_{EE} = -3.3V \pm 0.3V$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{EE}$	Supply Voltage		-3.0	-3.3	-3.8	V
$I_{EE}$	Power Supply Current				70	mA

**Table 2D. ECL DC Characteristics,  $V_{CC} = 0V$ ;  $V_{EE} = -3.3V \pm 0.3V$**

Symbol	Parameter	-40°C			25°C			85°C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$V_{OH}$	Output High Voltage	-1.125	-1.025	-0.92	-1.075	-1.005	-0.93	-1.005	-1.08	-0.935	V
$V_{OL}$	Output Low Voltage	-1.895	-1.755	-1.62	-1.875	-1.78	-1.685	-1.86	-1.765	-1.67	V
$V_{IH}$	Input High Voltage (Single-Ended)	-1.225		-0.94	-1.225		-0.94	-1.225			V
$V_{IL}$	Input Low Voltage (Single-Ended)	-1.87		-1.535	-1.87		-1.535	-1.87		-1.535	V
$V_{BB}$	Output Voltage Reference; NOTE 1	-1.44		-1.32	-1.44		-1.32	-1.44		-1.32	mV
$V_{PP}$	Peak-to-Peak Input Voltage	500		1000	500		1000	500		1000	mV
$V_{CMR}$	Input High Voltage Common Mode Range; NOTE 2	1.5		-0.4	1.5		-0.4	1.5		-0.4	V
$I_{IH}$	Input High Current			150			150			150	$\mu$ A
$I_{IL}$	Input Low Current	-150			-150			-150			$\mu$ A

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{CC} - 2V$ .

NOTE 2:  $V_{CMR}$  min varies 1:1 with  $V_{EE}$ , max varies 1:1 with  $V_{CC}$ .  $V_{CMR}$  is defined as the range within which the  $V_{IH}$  level may vary, with the device still meeting the propagation delay specification. The  $V_{IL}$  level must be such that the peak-to-peak voltage is less than 1V and greater than or equal to  $V_{PP}(\min)$ .

**TABLE 3. AC CHARACTERISTICS,  $V_{CC} = 3.3V$ ;  $V_{EE} = 0V$  OR  $V_{CC} = 0V$ ;  $V_{EE} = -3.3V$**

Symbol	Parameter	-40°C			25°C			85°C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$f_{MAX}$	Output Frequency		>2			>2			>2		GHz
$t_{PD}$	Propagation Delay; NOTE 1	700		900	750		950	775		975	ps
$t_{sk(o)}$	Output Skew; NOTE 2, 4			75			50			50	ps
$t_{sk(pp)}$	Part-to-Part Skew; NOTE 3, 4			250			200			200	ps
$t_R/t_F$	Output Rise/Fall Time	20% to 80%	100	400	100		400	100		400	ps

$V_{EE}$  can vary  $\pm 0.3V$ .

All parameters measured at  $f \leq 1.2GHz$  unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the differential output crossing point.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions.

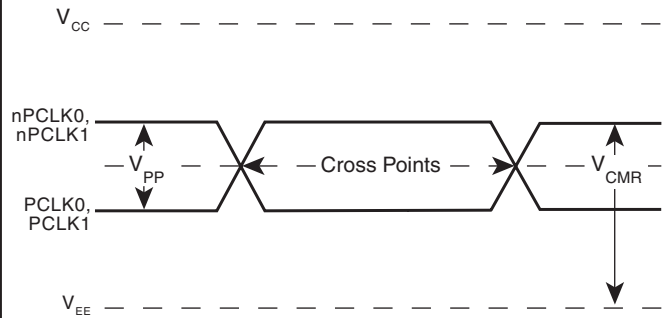
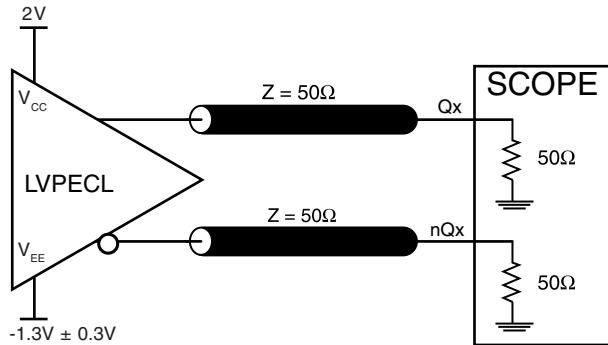
Measured at the output differential cross points.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

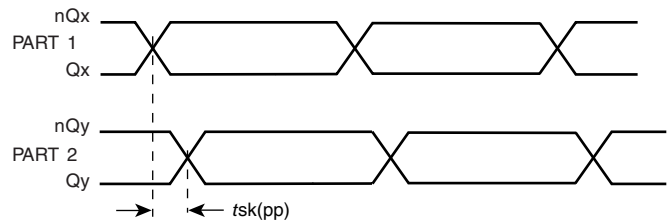
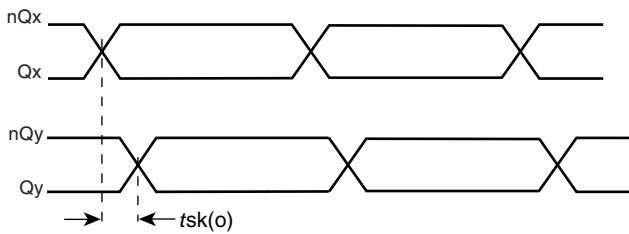


## PARAMETER MEASUREMENT INFORMATION



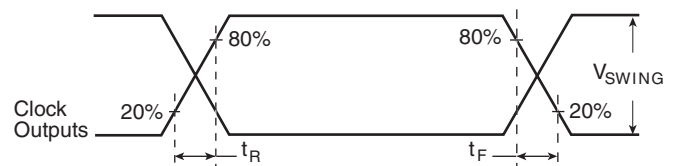
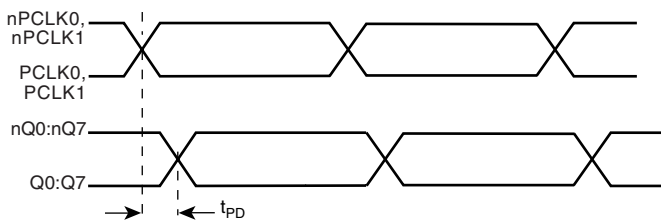
### OUTPUT LOAD AC TEST CIRCUIT

### DIFFERENTIAL INPUT LEVEL



### OUTPUT SKEW

### PART-TO-PART SKEW



### PROPAGATION DELAY

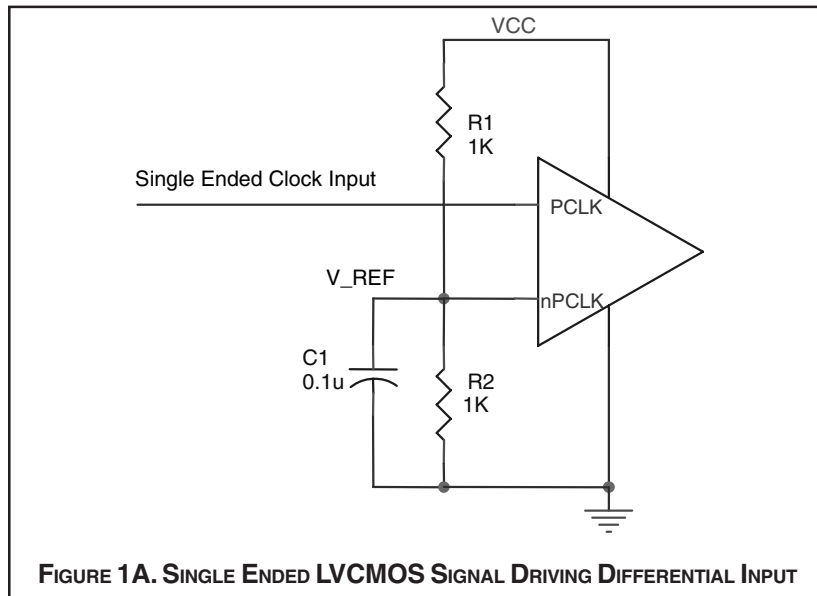
### OUTPUT RISE/FALL TIME



## APPLICATION INFORMATION

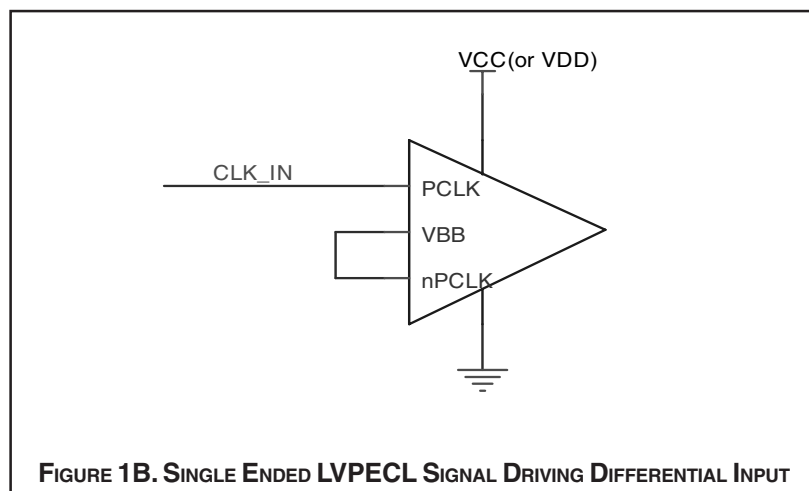
### WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LVC MOS LEVELS

Figure 1A shows an example of the differential input that can be wired to accept single ended LVC MOS levels. The reference voltage level  $V_{BB}$  generated from the device is connected to the negative input. The C1 capacitor should be located as close as possible to the input pin.



### WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LVPECL LEVELS

Figure 1B shows an example of the differential input that can be wired to accept single ended LVPECL levels. The reference voltage level  $V_{BB}$  generated from the device is connected to the negative input.

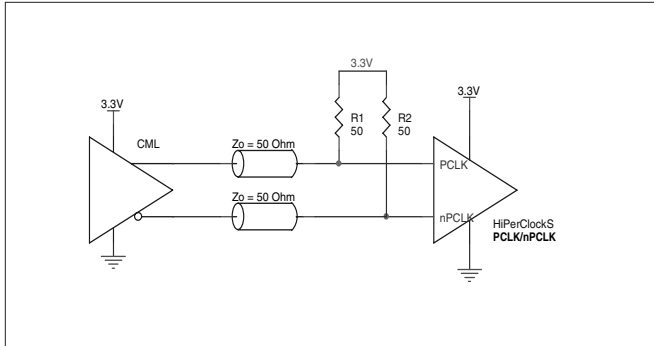




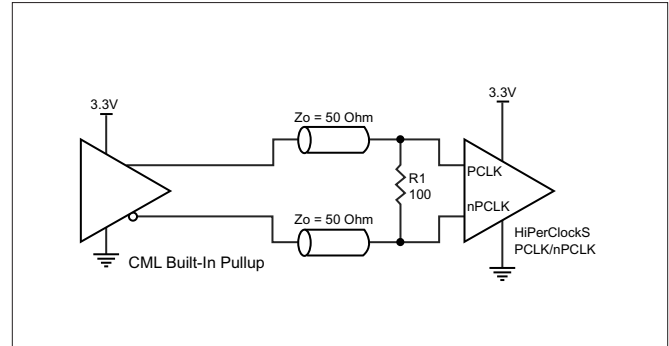
### LVPECL CLOCK INPUT INTERFACE

The PCLK /nPCLK accepts LVPECL, CML, SSTL and other differential signals. Both  $V_{SWING}$  and  $V_{OH}$  must meet the  $V_{PP}$  and  $V_{CMR}$  input requirements. Figures 2A to 2F show interface examples for the HiPerClockS PCLK/nPCLK input driven by the most common driver types. The input inter-

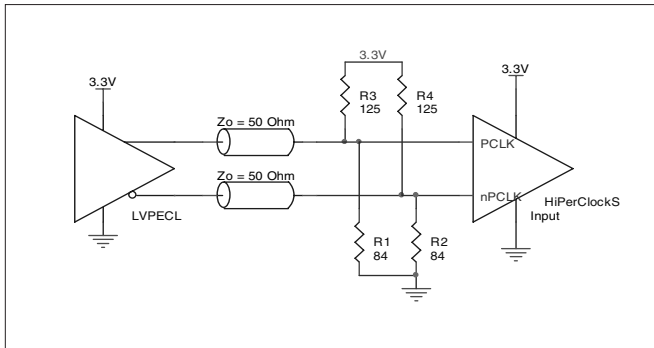
faces suggested here are examples only. If the driver is from another vendor, use their termination recommendation. Please consult with the vendor of the driver component to confirm the driver termination requirements.



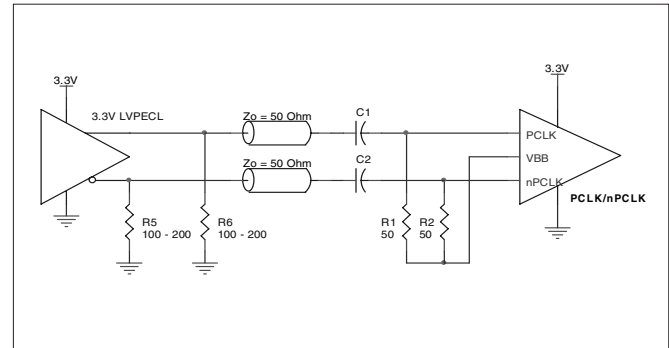
**FIGURE 2A. HiPerClockS PCLK/nPCLK INPUT DRIVEN BY AN OPEN COLLECTOR CML DRIVER**



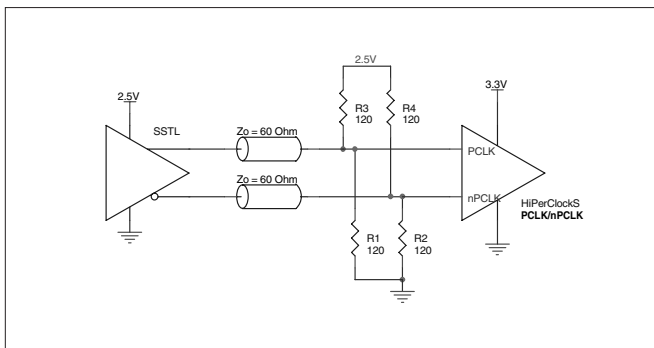
**FIGURE 2B. HiPerClockS PCLK/nPCLK INPUT DRIVEN BY A BUILT-IN PULLUP CML DRIVER**



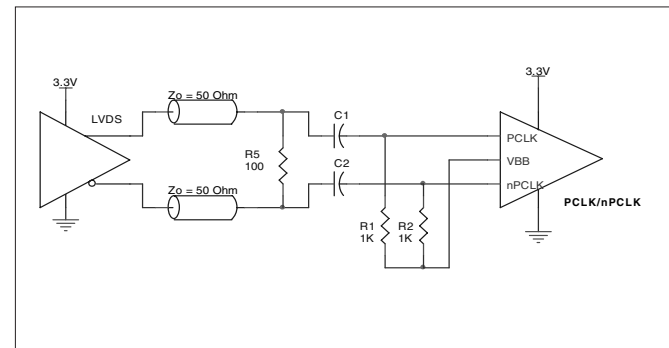
**FIGURE 2C. HiPerClockS PCLK/nPCLK INPUT DRIVEN BY A 3.3V LVPECL DRIVER**



**FIGURE 2D. HiPerClockS PCLK/nPCLK INPUT DRIVEN BY A 3.3V LVPECL DRIVER WITH AC COUPLE**



**FIGURE 2E. HiPerClockS PCLK/nPCLK INPUT DRIVEN BY AN SSTL DRIVER**



**FIGURE 2F. HiPerClockS PCLK/nPCLK INPUT DRIVEN BY A 3.3V LVDS DRIVER**



## RECOMMENDATIONS FOR UNUSED INPUT AND OUTPUT PINS

### INPUTS:

#### PCLK/nPCLK INPUT:

For applications not requiring the use of a differential input, both the PCLK and nPCLK pins can be left floating. Though not required, but for additional protection, a 1kΩ resistor can be tied from PCLK to ground.

#### LVC MOS CONTROL PINS:

All control pins have internal pull-ups or pull-downs; additional resistance is not required but can be added for additional protection. A 1kΩ resistor can be used.

### OUTPUTS:

#### LVPECL OUTPUT

All unused LVPECL outputs can be left floating. We recommend that there is no trace attached. Both sides of the differential output pair should either be left floating or terminated.

## TERMINATION FOR LVPECL OUTPUTS

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

FOUT and nFOUT are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive 50Ω transmission lines. Matched imped-

ance techniques should be used to maximize operating frequency and minimize signal distortion. *Figures 3A and 3B* show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

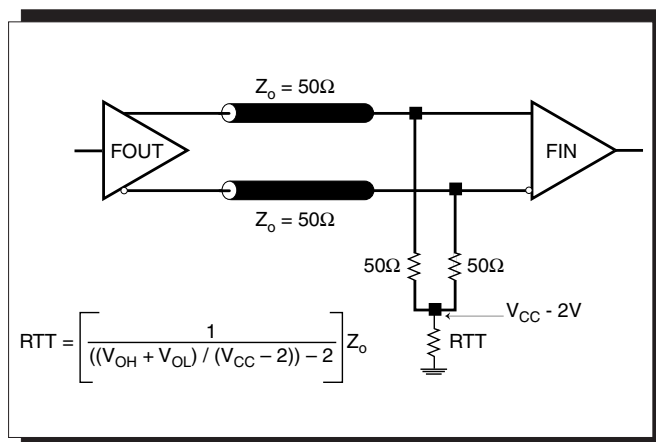


FIGURE 3A. LVPECL OUTPUT TERMINATION

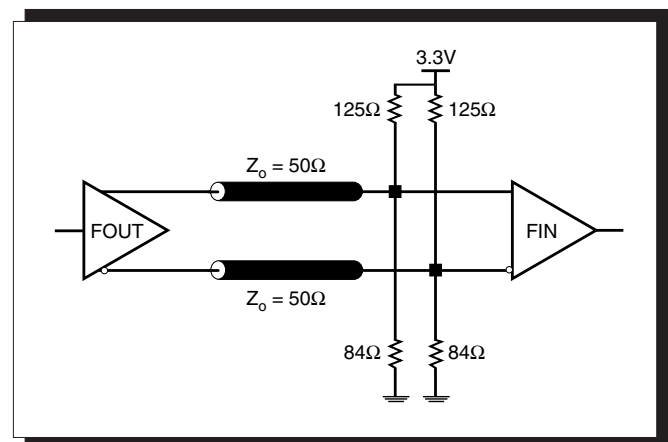


FIGURE 3B. LVPECL OUTPUT TERMINATION







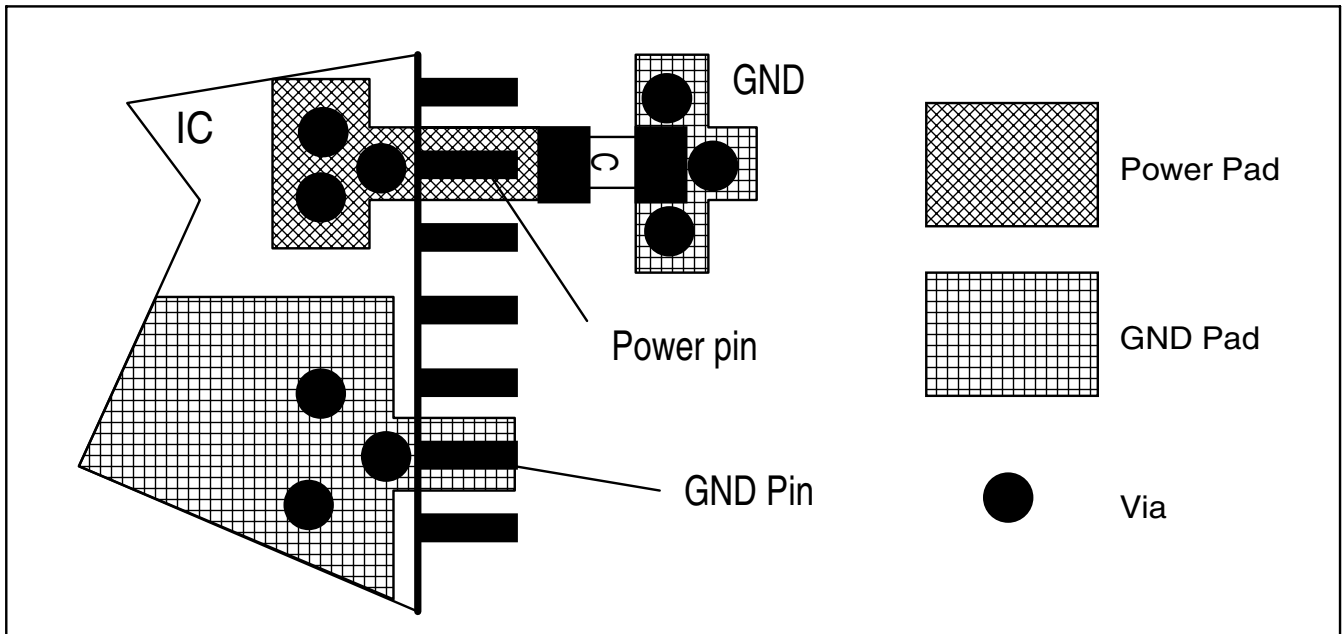
**POWER, GROUND AND BYPASS CAPACITOR**

This section provides a layout guide related to power, ground and placement of bypass capacitors for a high-speed digital IC. This layout guide is a general recommendation. The actual board design will depend on the component types being used, the board density and cost constraints. This description assumes that the board has clean power and ground planes. The goal is to minimize the ESR between the clean power/ground plane and the IC power/ground pin.

A low ESR bypass capacitor should be used on each power pin. The value of bypass capacitors ranges from 0.01uF to 0.1uF. The bypass capacitors should be located as close to the power

pin as possible. It is preferable to locate the bypass capacitor on the same side as the IC. *Figure 4B* shows suggested capacitor placement. Placing the bypass capacitor on the same side as the IC allows the capacitor to have direct contact with the IC power pin. This can avoid any vias between the bypass capacitor and the IC power pins.

The vias should be placed at the Power/Ground pads. There should be a minimum of one via per pin. Increasing the number of vias from the Power/Ground pads to Power/Ground planes can improve the conductivity.



**FIGURE 4B. RECOMMENDED LAYOUT OF BYPASS CAPACITOR PLACEMENT**



## POWER CONSIDERATIONS

This section provides information on power dissipation and junction temperature for the ICS853310. Equations and example calculations are also provided.

### 1. Power Dissipation.

The total power dissipation for the ICS853310 is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for  $V_{CC} = 3.8V$ , which gives worst case results.

**NOTE:** Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)<sub>MAX</sub> =  $V_{CC\_MAX} * I_{EE\_MAX} = 3.8V * 70mA = 266mW$
- Power (outputs)<sub>MAX</sub> = **30.94mW/Loaded Output pair**  
If all outputs are loaded, the total power is  $8 * 30.94mW = 247.5mW$

$$\text{Total Power}_{MAX} (3.8V, \text{ with all outputs switching}) = 266mW + 247.5mW = 513.5mW$$

### 2. Junction Temperature.

Junction temperature,  $T_j$ , is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS™ devices is 125°C.

The equation for  $T_j$  is as follows:  $T_j = \theta_{JA} * Pd\_total + T_A$

$T_j$  = Junction Temperature

$\theta_{JA}$  = Junction-to-Ambient Thermal Resistance

$Pd\_total$  = Total Device Power Dissipation (example calculation is in section 1 above)

$T_A$  = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance  $\theta_{JA}$  must be used. Assuming a moderate air flow of 200 linear feet per minute and a multi-layer board, the appropriate value is 31.1°C/W per Table 4 below.

Therefore,  $T_j$  for an ambient temperature of 85°C with all outputs switching is:

$$85^\circ C + 0.514W * 31.1^\circ C/W = 101^\circ C. \text{ This is well below the limit of } 125^\circ C.$$

This calculation is only an example.  $T_j$  will obviously vary depending on the number of loaded outputs, supply voltage, air flow, and the type of board (single layer or multi-layer).

**TABLE 4. THERMAL RESISTANCE  $\theta_{JA}$  FOR 28-PIN PLCC, FORCED CONVECTION**

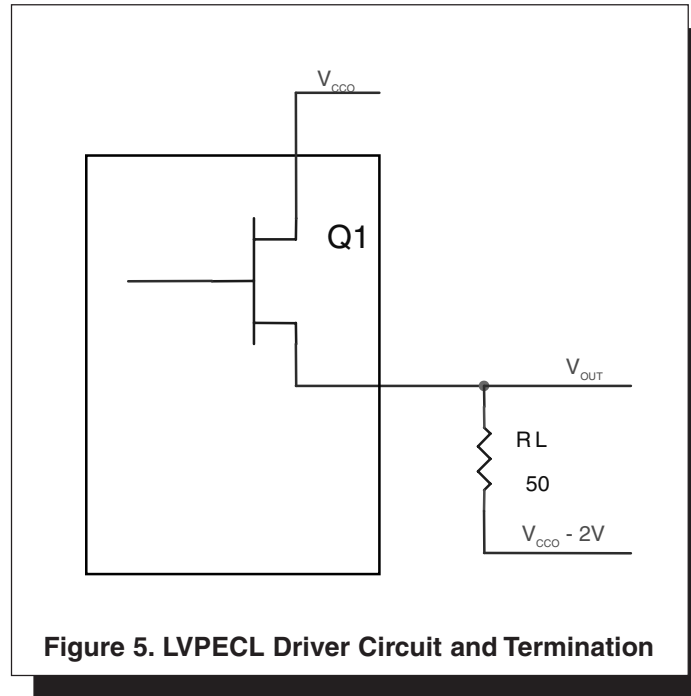
	$\theta_{JA}$ by Velocity (Linear Feet per Minute)		
	0	200	500
Multi-Layer PCB, JEDEC Standard Test Boards	37.8°C/W	31.1°C/W	28.3°C/W

**NOTE:** Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.



### 3. Calculations and Equations.

LVPECL output driver circuit and termination are shown in Figure 5.



**Figure 5. LVPECL Driver Circuit and Termination**

To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of  $V_{CCO} - 2V$ .

- For logic high,  $V_{OUT} = V_{OH\_MAX} = V_{CCO\_MAX} - 0.935V$

$$(V_{CCO\_MAX} - V_{OH\_MAX}) = 0.935V$$

- For logic low,  $V_{OUT} = V_{OL\_MAX} = V_{CCO\_MAX} - 1.67V$

$$(V_{CCO\_MAX} - V_{OL\_MAX}) = 1.67V$$

$Pd\_H$  is power dissipation when the output drives high.

$Pd\_L$  is the power dissipation when the output drives low.

$$Pd\_H = [(V_{OH\_MAX} - (V_{CCO\_MAX} - 2V))/R_L] * (V_{CCO\_MAX} - V_{OH\_MAX}) = [(2V - (V_{CCO\_MAX} - V_{OH\_MAX}))/R_L] * (V_{CCO\_MAX} - V_{OH\_MAX}) = [(2V - 0.935V)/50\Omega] * 0.935V = 19.92mW$$

$$Pd\_L = [(V_{OL\_MAX} - (V_{CCO\_MAX} - 2V))/R_L] * (V_{CCO\_MAX} - V_{OL\_MAX}) = [(2V - (V_{CCO\_MAX} - V_{OL\_MAX}))/R_L] * (V_{CCO\_MAX} - V_{OL\_MAX}) = [(2V - 1.67V)/50\Omega] * 1.67V = 11.02mW$$

$$\text{Total Power Dissipation per output pair} = Pd\_H + Pd\_L = 30.94mW$$



## RELIABILITY INFORMATION

TABLE 5.  $\theta_{JA}$  vs. AIR FLOW TABLE FOR 28 LEAD PLCC

$\theta_{JA}$ by Velocity (Linear Feet per Minute)			
	0	200	500
Multi-Layer PCB, JEDEC Standard Test Boards	37.8°C/W	31.1°C/W	28.3°C/W

**NOTE:** Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

### TRANSISTOR COUNT

The transistor count for ICS853310 is: 462

Pin compatible with MC100LVE310



PACKAGE OUTLINE - V SUFFIX FOR 28 LEAD PLCC

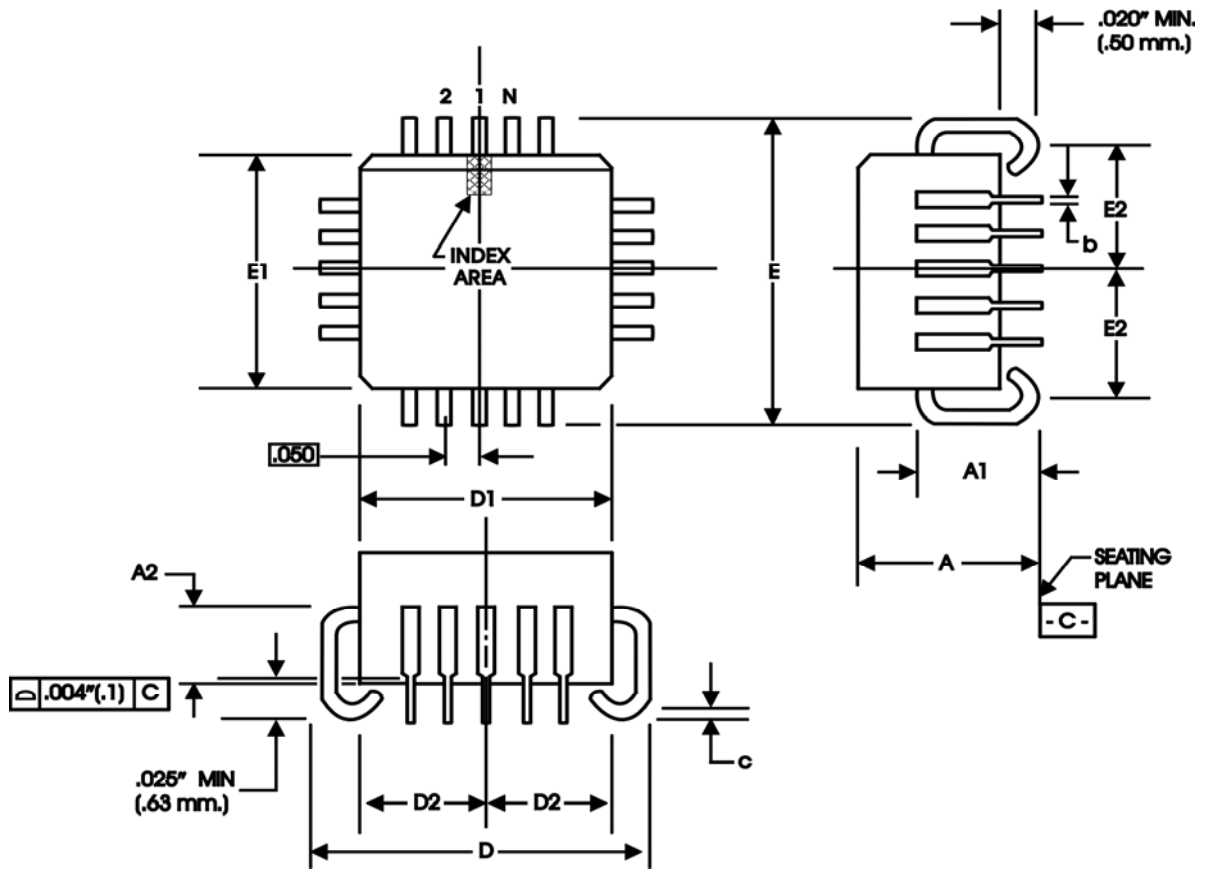


TABLE 6. PACKAGE DIMENSIONS

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS		
SYMBOL	MINIMUM	MAXIMUM
N	28	
A	4.19	4.57
A1	2.29	3.05
A2	1.57	2.11
b	0.33	0.53
c	0.19	0.32
D	12.32	12.57
D1	11.43	11.58
D2	4.85	5.56
E	12.32	12.57
E1	11.43	11.58
E2	4.85	5.56

Reference Document: JEDEC Publication 95, MS-018



Integrated  
Circuit  
Systems, Inc.

# ICS853310

## LOW SKEW, 1-TO-8 DIFFERENTIAL-TO-3.3V LVPECL/ECL FANOUT BUFFER

**TABLE 7. ORDERING INFORMATION**

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
853310AV	ICS853310AV	28 Lead PLCC	Tube	-40°C to 85°C
853310AVT	ICS853310AV	28 Lead PLCC on Tape and Reel	500 Tape & Reel	-40°C to 85°C
853310AVLF	ICS853310AVL	28 Lead "Lead-Free" PLCC	Tube	-40°C to 85°C
853310AVLFT	ICS853310AVL	28 Lead "Lead-Free" PLCC	500 Tape & Reel	-40°C to 85°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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**ICS853310**

LOW SKEW, 1-TO-8

DIFFERENTIAL-TO-3.3V LVPECL/ECL FANOUT BUFFER

REVISION HISTORY SHEET

Rev	Table	Page	Description of Change	Date
A	T7	1	Add Lead-Free bullet. Corrected Pin Assignment pin number spacing.	9/14/05
		8	Added <i>Recommendations for Unused Input and Output Pins</i> .	
		15	Ordering Information Table - added Lead-Free Part Number.	
A	T7	15	Ordering Information Table - added Lead-Free marking.	11/22/05